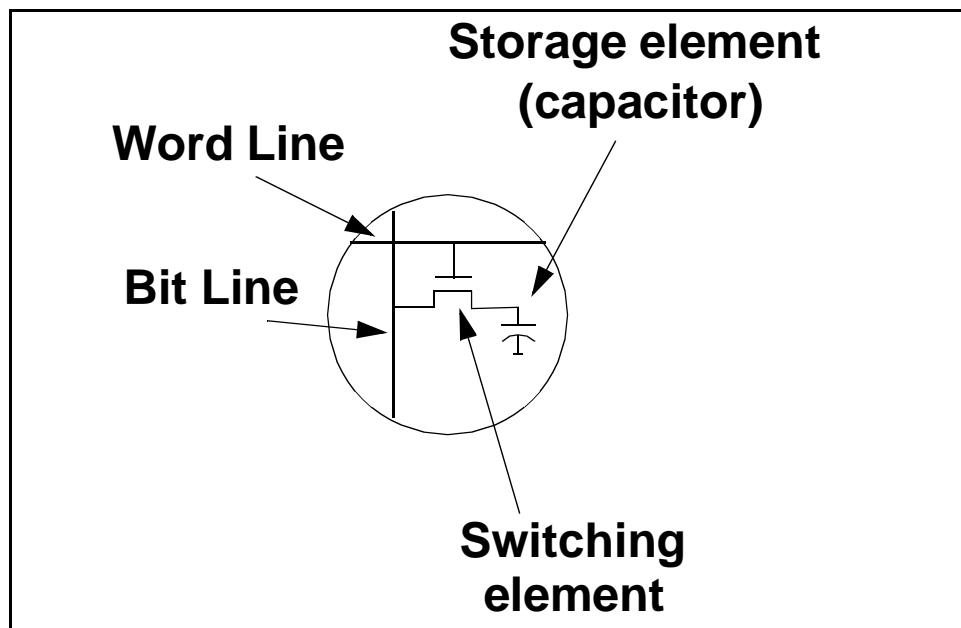


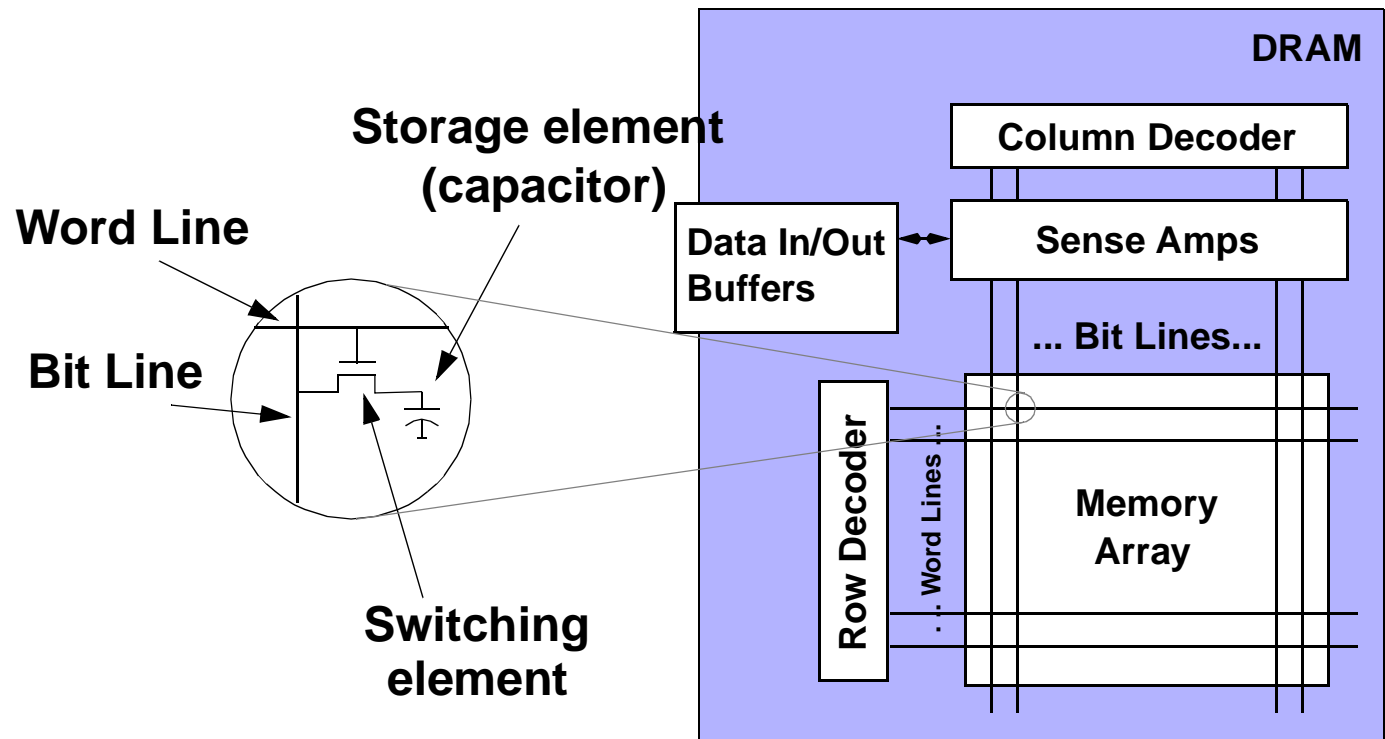
# DRAM Circuit and Architecture Basics

- **Overview**
- **Terminology**
- **Access Protocol**
- **Architecture**



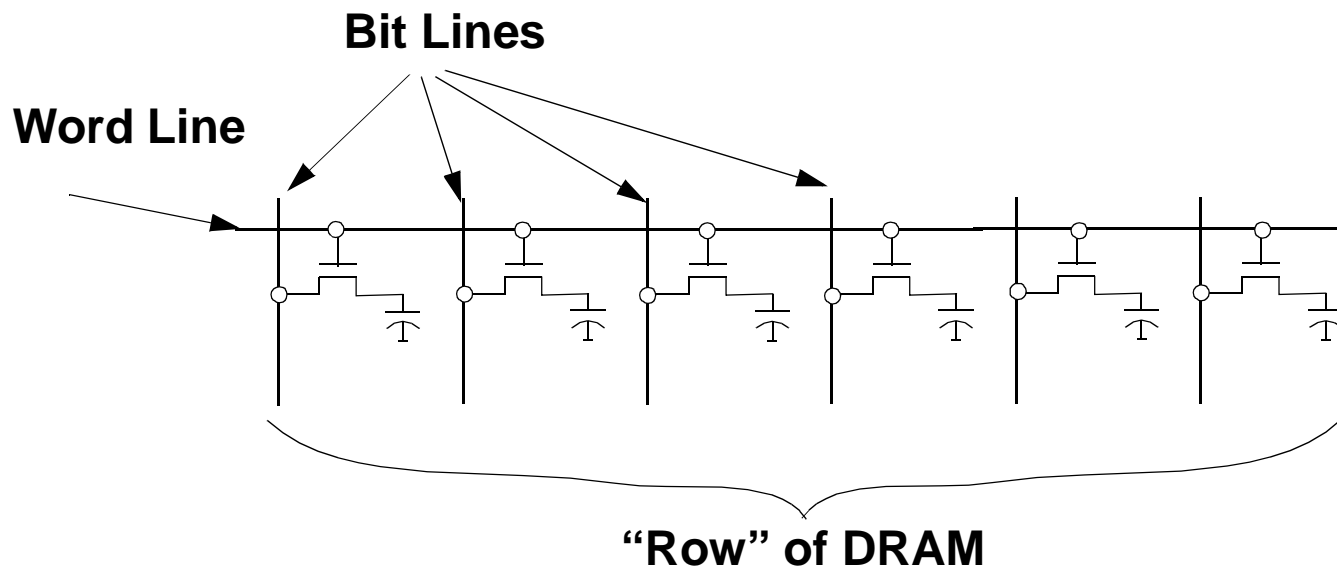
# DRAM Circuit Basics

## DRAM Cell



# DRAM Circuit Basics

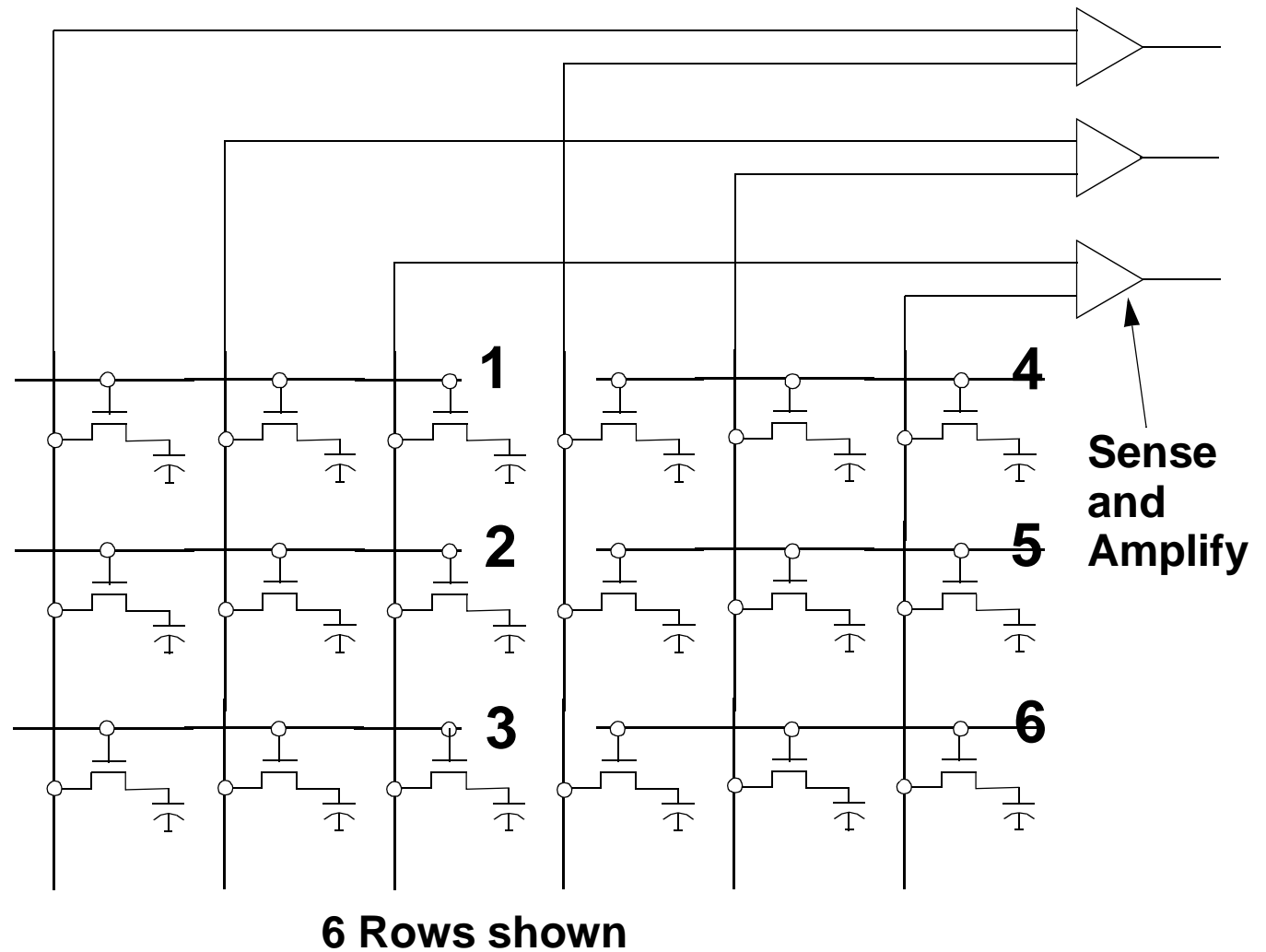
## “Row” Defined



**Row Size: 8 Kb @ 256 Mb SDRAM node**  
**4 Kb @ 256 Mb RDRAM node**

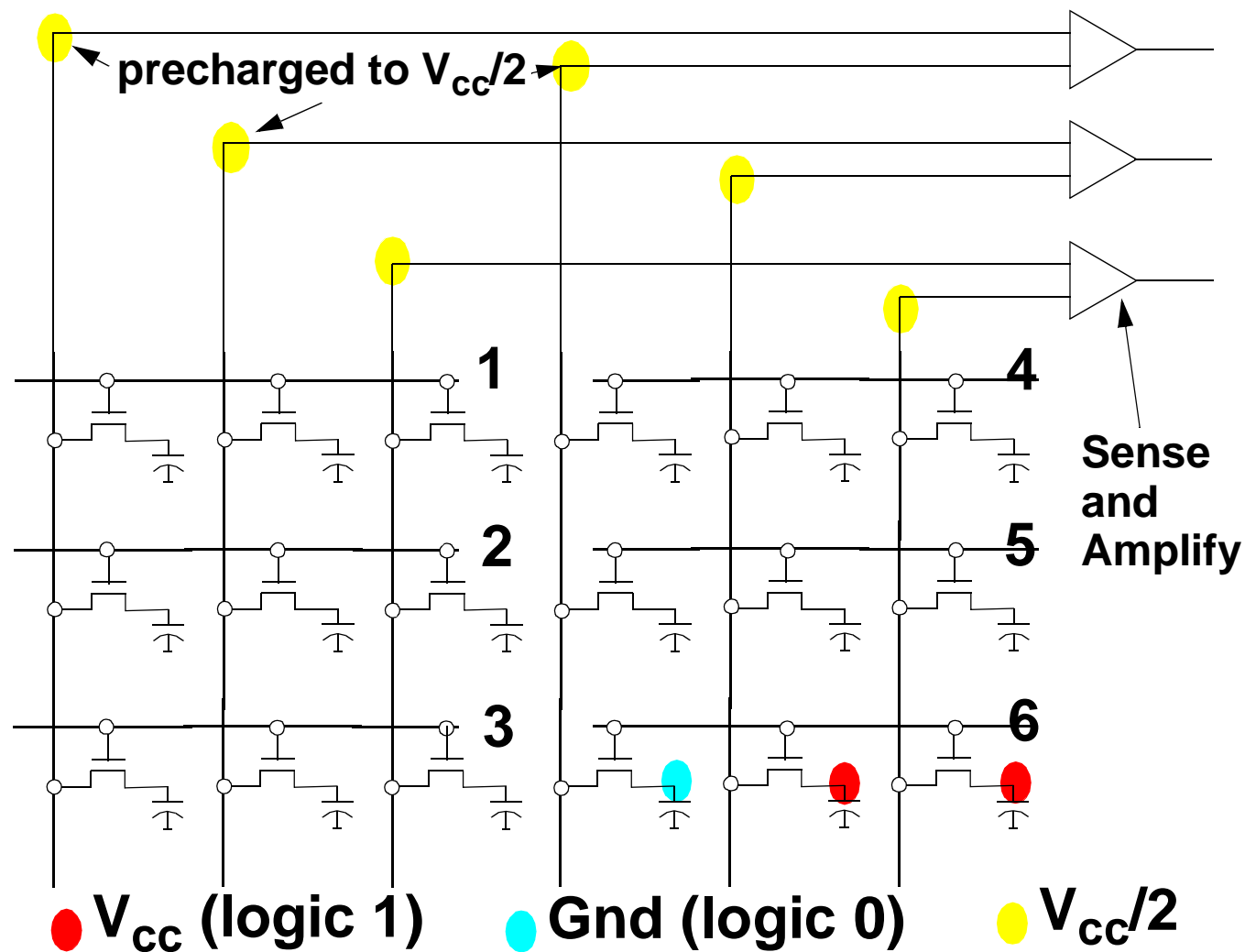
# DRAM Circuit Basics

## Sense Amplifier I



# DRAM Circuit Basics

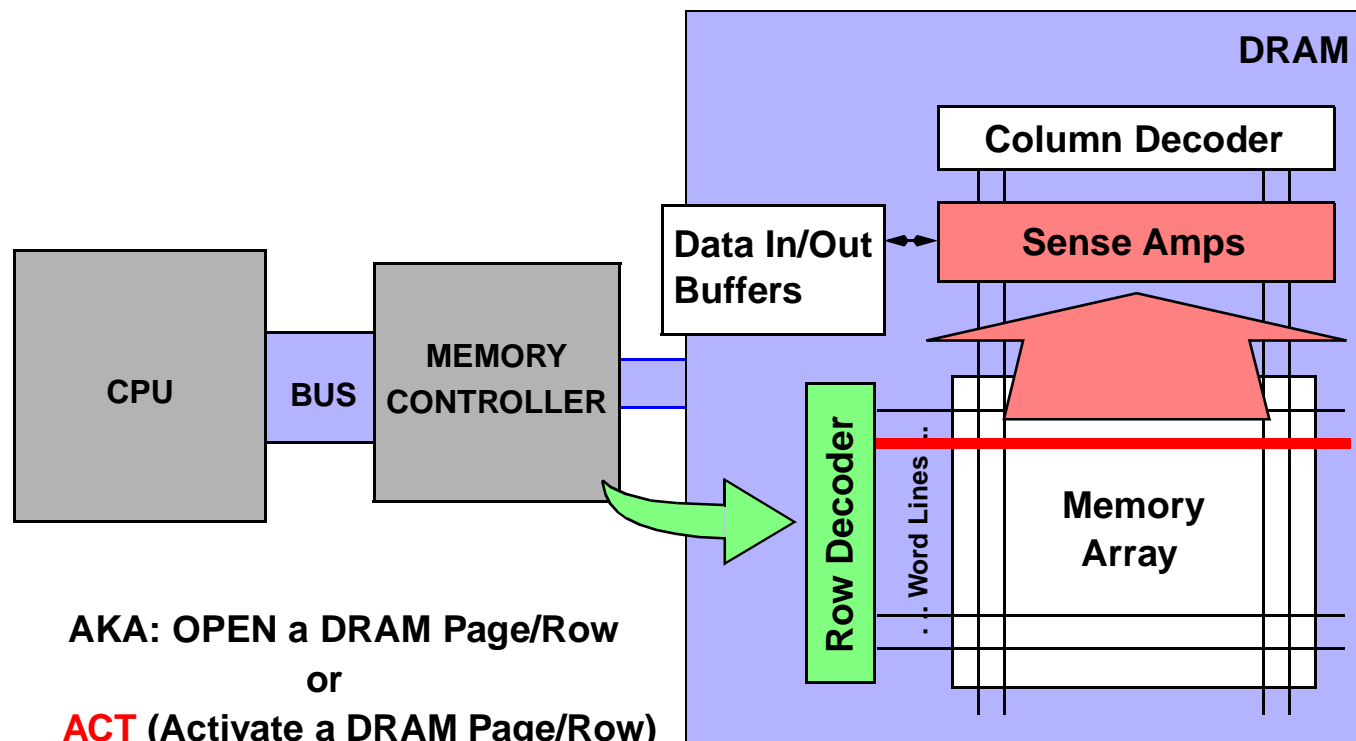
## Sense Amplifier II : Precharged





# DRAM Access Protocol

## ROW ACCESS



AKA: OPEN a DRAM Page/Row  
or  
**ACT** (Activate a DRAM Page/Row)  
or  
**RAS** (Row Address Strobe)

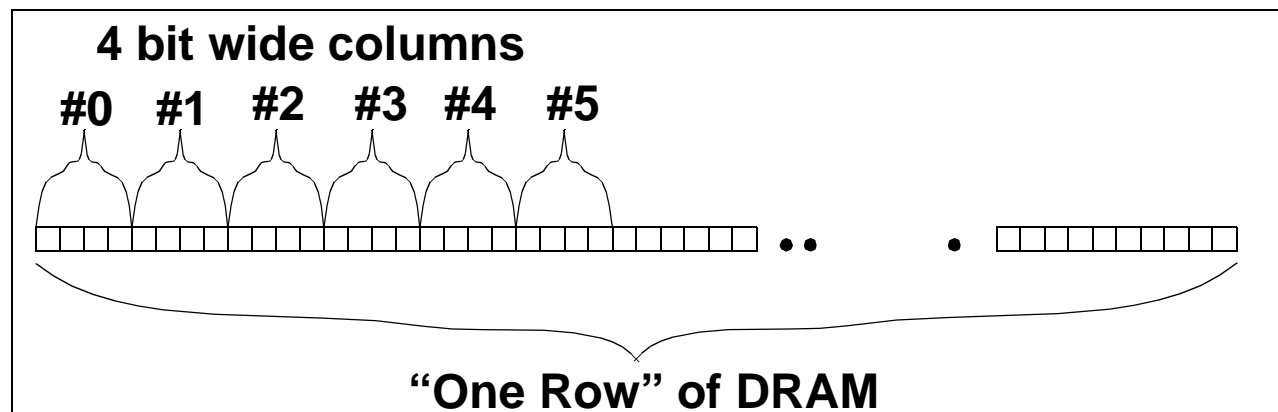
# DRAM Circuit Basics

## “Column” Defined

**Column: Smallest addressable quantity of DRAM on chip**

**SDRAM\*: column size == chip data bus width (4, 8, 16, 32)**  
**RDRAM: column size != chip data bus width (128 bit fixed)**

**SDRAM\*: get “n” columns per access. n = (1, 2, 4, 8)**  
**RDRAM: get 1 column per access.**

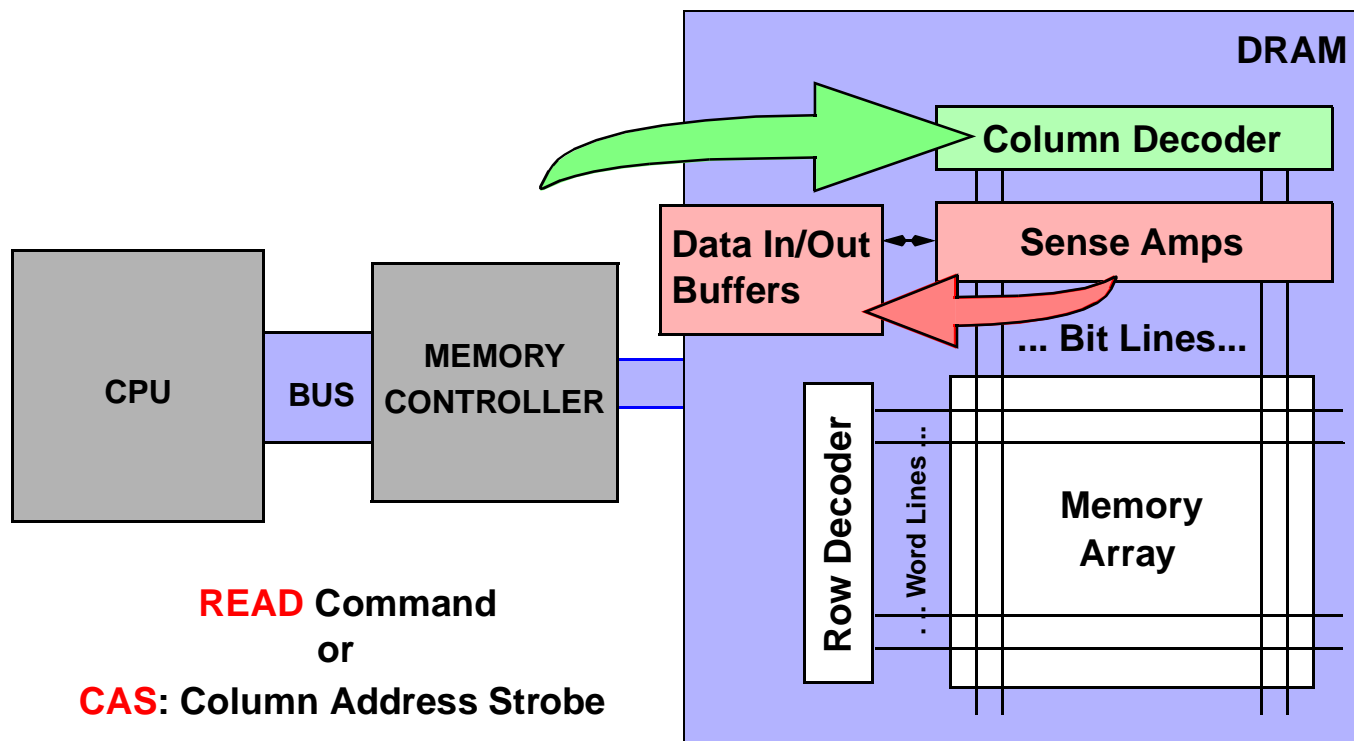


**\* SDRAM means SDRAM and variants. i.e. DDR SDRAM**



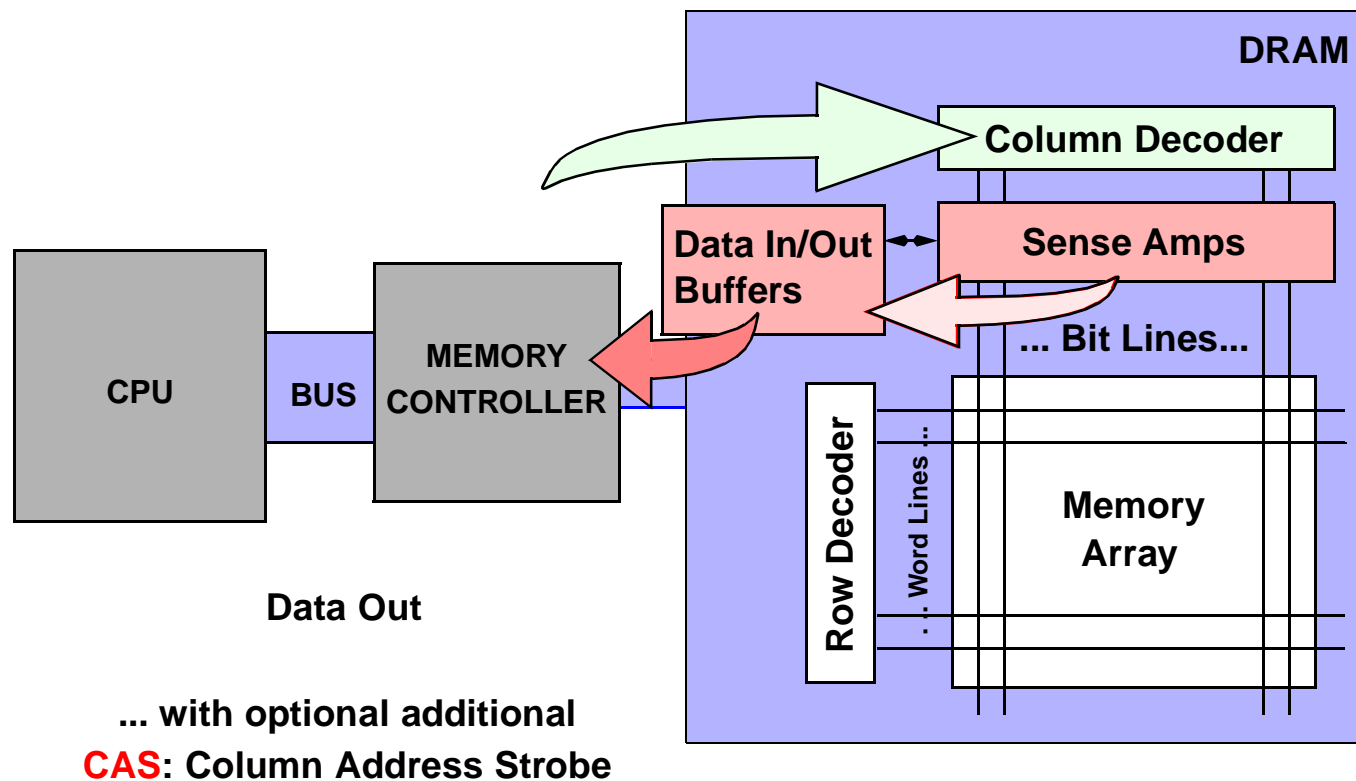
# DRAM Access Protocol

## COLUMN ACCESS I



# DRAM Access Protocol

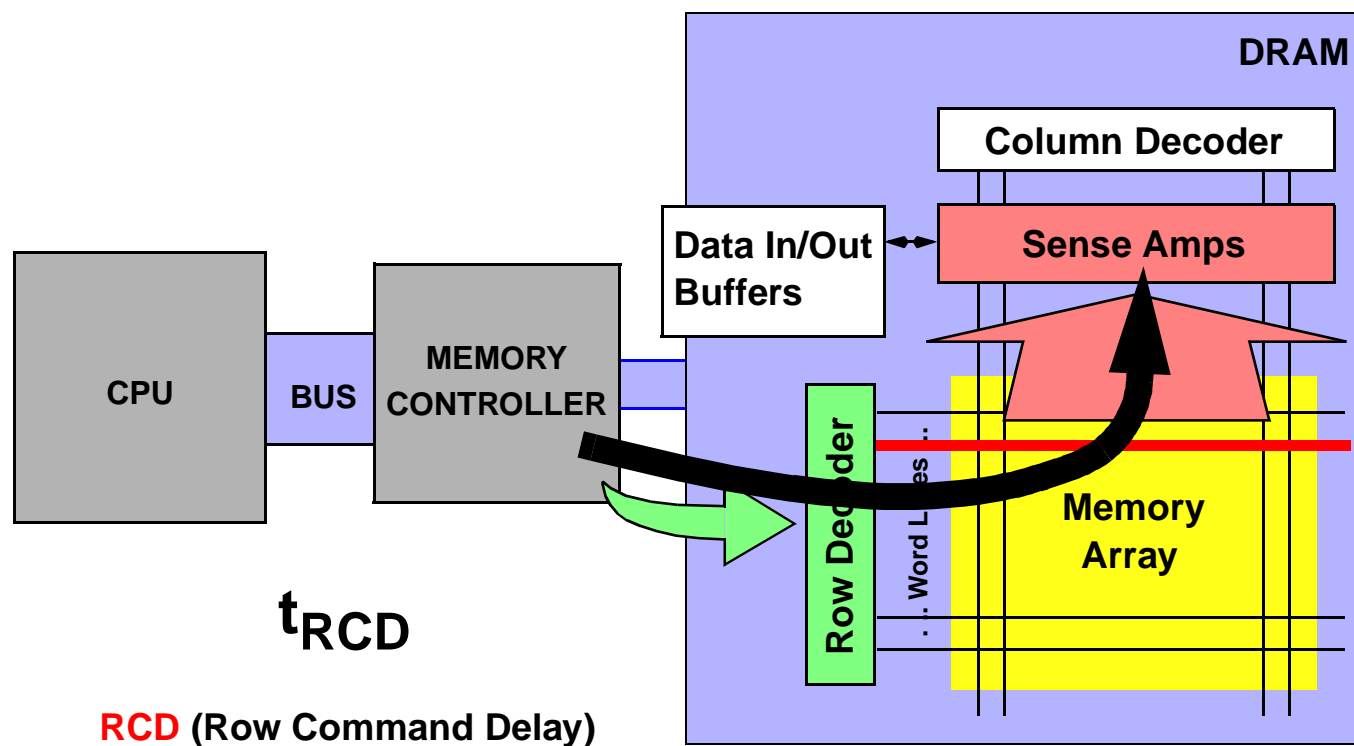
## Column Access II



**note: page mode enables overlap with CAS**

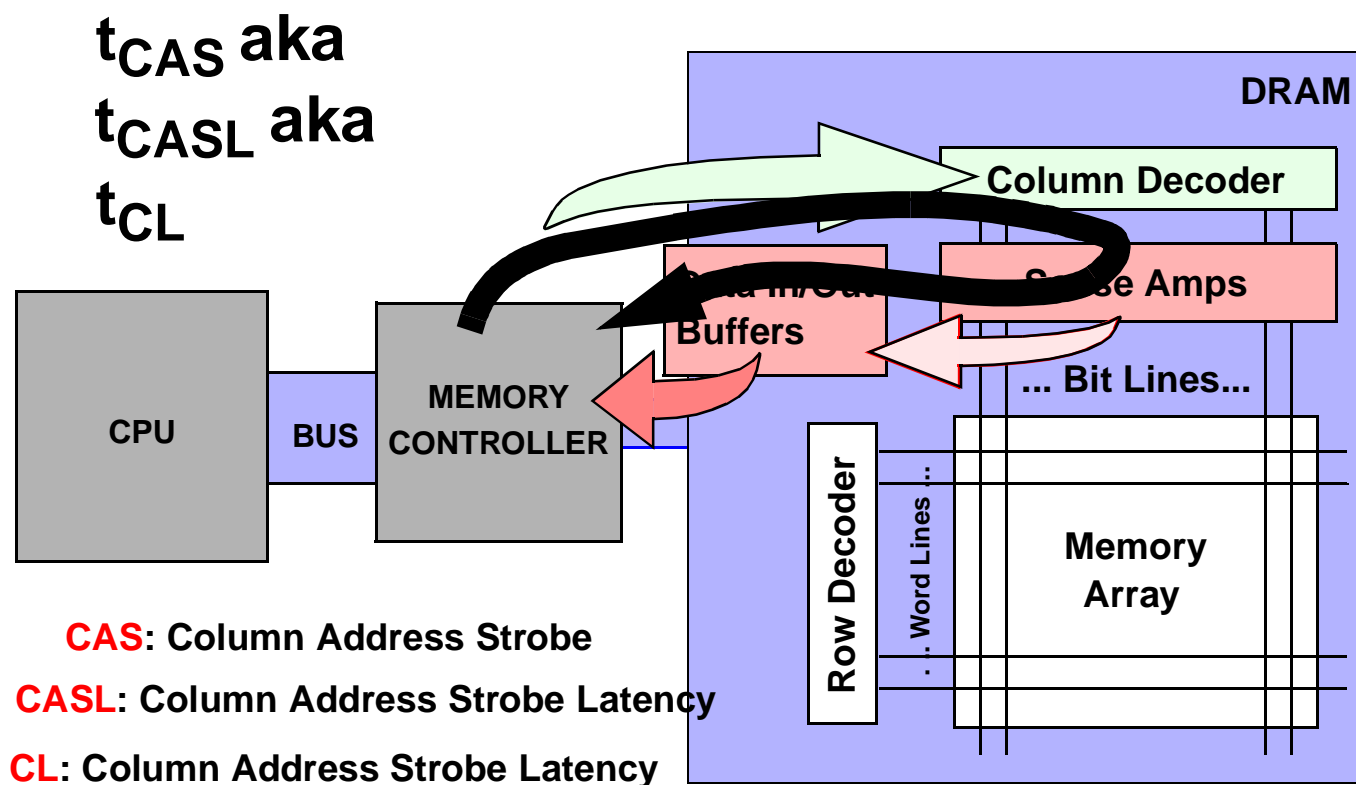
# DRAM "Speed" Part I

How fast can I move data from DRAM cell to sense amp?



# DRAM “Speed” Part II

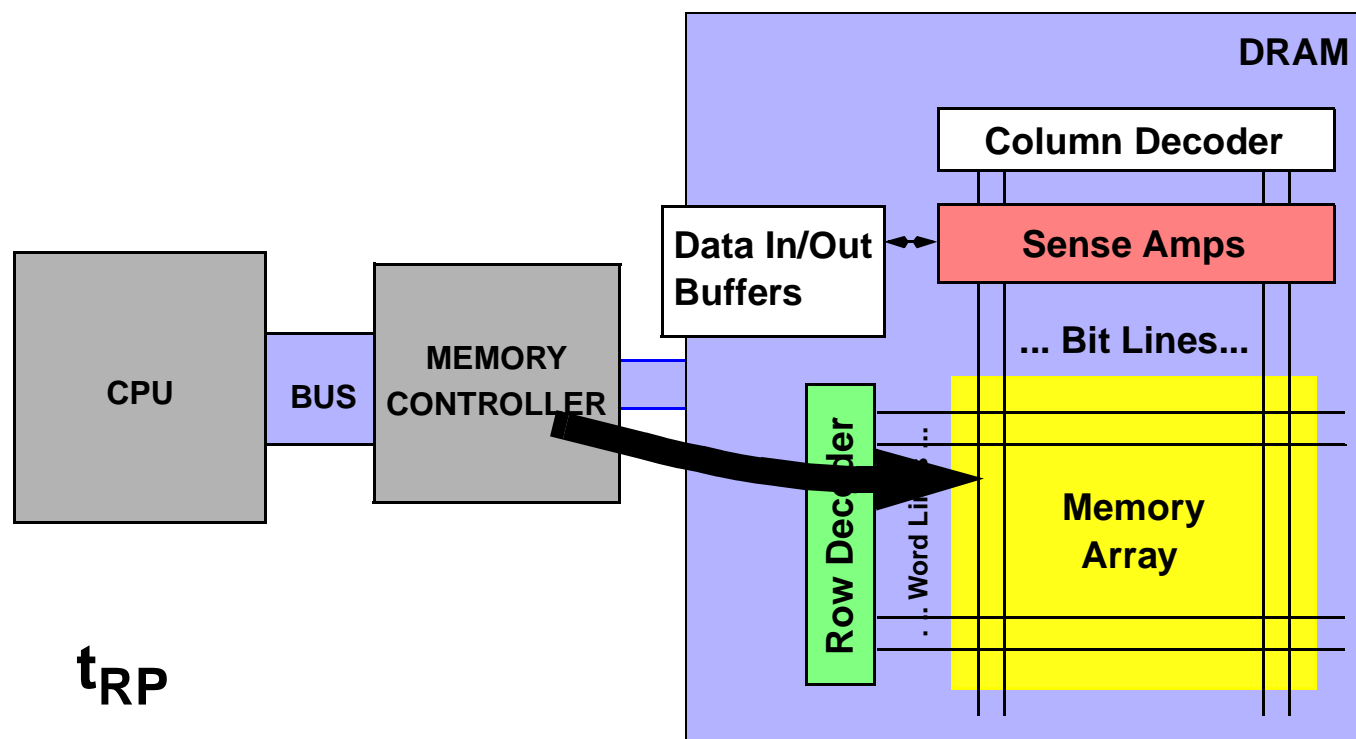
How fast can I get data out of sense amps  
back into memory controller?





# DRAM "Speed" Part IV

How fast can I precharge DRAM array so I can engage another RAS?

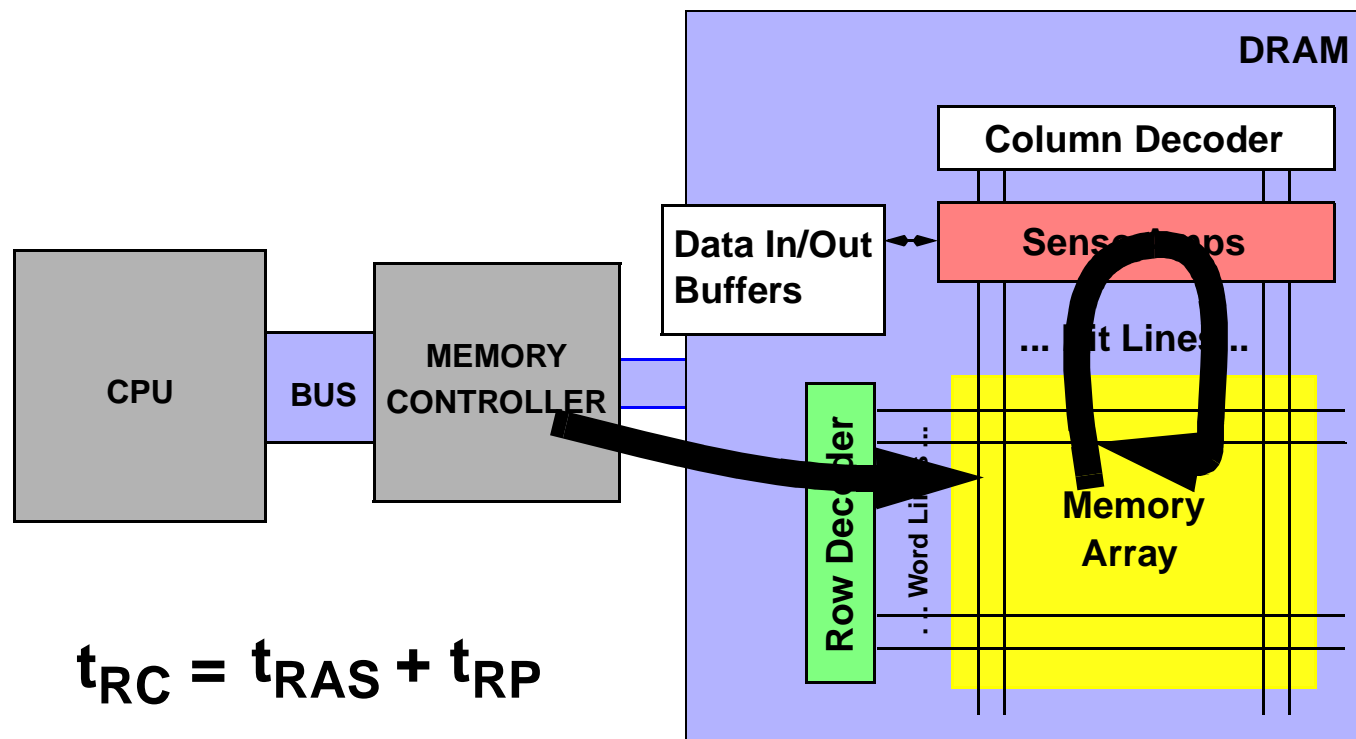


$t_{RP}$

**RP** (Row Precharge Delay)

# DRAM "Speed" Part V

How fast can I read from different rows?



$$t_{RC} = t_{RAS} + t_{RP}$$

**RC** (Row Cycle Time)

# DRAM “Speed” Summary I

## What do I care about?

$t_{RCD}$

$t_{CAS}$

$t_{RP}$

$t_{RC} = t_{RAS} + t_{RP}$

$t_{RAC} = t_{RCD} + t_{CAS}$

Seen in ads.  
Easy to explain  
Easy to sell

Embedded systems designers  
DRAM manufacturers

Computer Architect:  
Latency bound code  
i.e. linked list traversal

**RAS**: Row Address Strobe

**CAS**: Column Address Strobe

**RCD**: Row Command Delay

**RAC**: Random Access Delay

**RP**: Row Precharge Delay

**RC**: Row Cycle Time



# DRAM “Speed” Summary II


DRAM Type	Frequency	Data Bus Width (per chip)	Peak Data Bandwidth (per Chip)	Random Access Time ( $t_{RAC}$ )	Row Cycle Time ( $t_{RC}$ )
PC133 SDRAM	133	16	200 MB/s	45 ns	60 ns
DDR 266	133 * 2	16	532 MB/s	45 ns	60 ns
PC800 RDRAM	400 * 2	16	1.6 GB/s	60 ns	70 ns
FCRAM	200 * 2	16	0.8 GB/s	25 ns	25 ns
RLDRAM	300 * 2	32	2.4 GB/s	25 ns	25 ns

**DRAM is “slow”**  
**But doesn’t have to be**  
 **$t_{RC} < 10ns$  achievable**

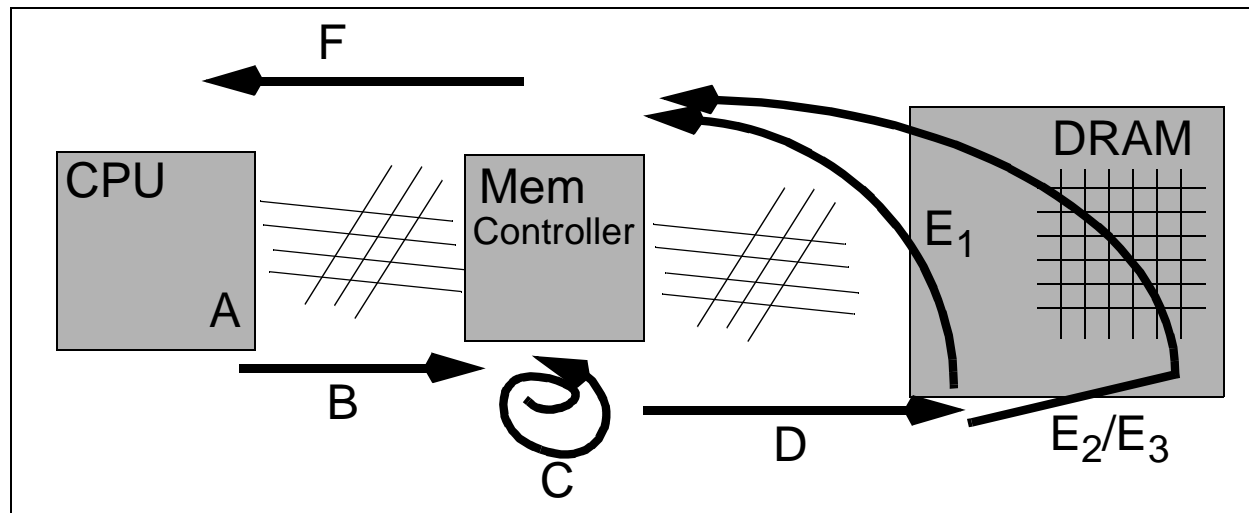


**Higher die cost** → **Not adopted in standard**

**Not commodity** → **Expensive**



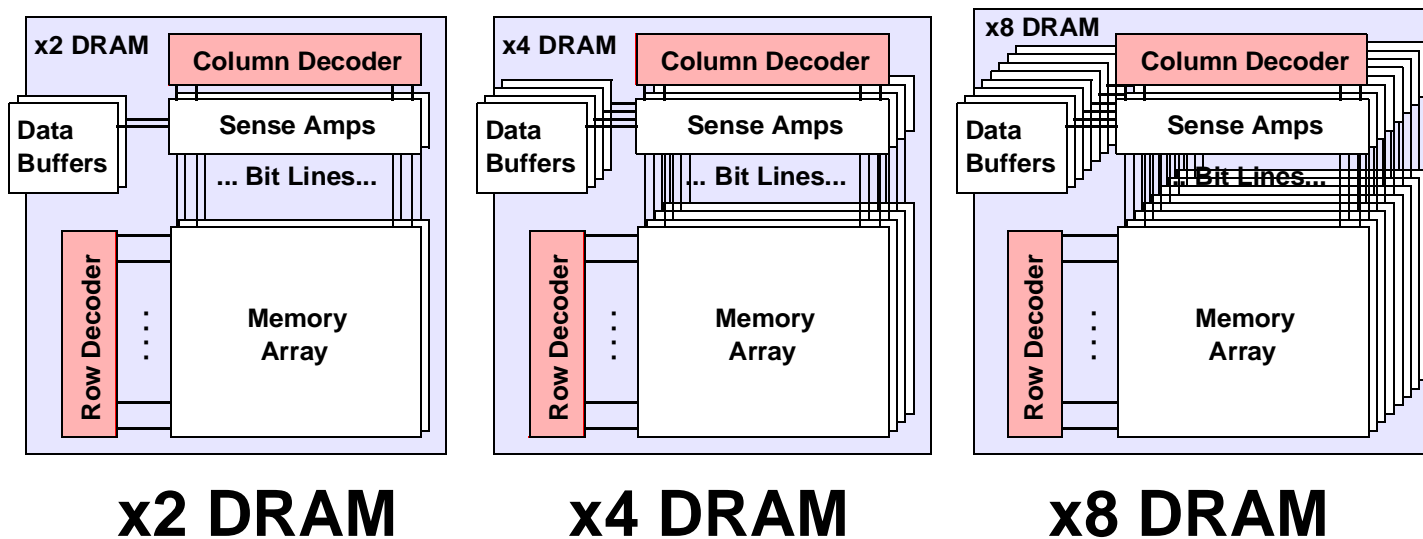
# “DRAM latency”



- A: Transaction request may be delayed in Queue
  - B: Transaction request sent to Memory Controller
  - C: Transaction converted to Command Sequences  
(may be queued)
  - D: Command/s Sent to DRAM
  - E<sub>1</sub>: Requires only a **CAS** or
  - E<sub>2</sub>: Requires **RAS + CAS** or
  - E<sub>3</sub>: Requires **PRE + RAS + CAS**
  - F: Transaction sent back to CPU
- “DRAM Latency” = A + B + C + D + E + F

# DRAM Architecture Basics

## PHYSICAL ORGANIZATION

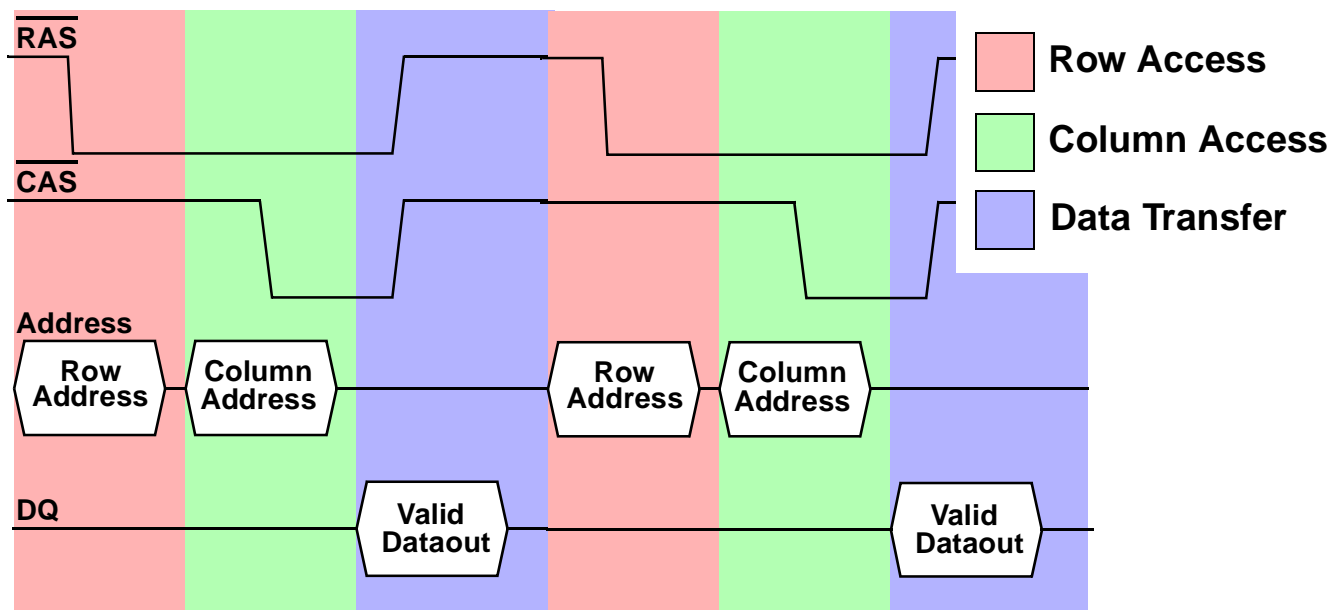


This is per bank ...

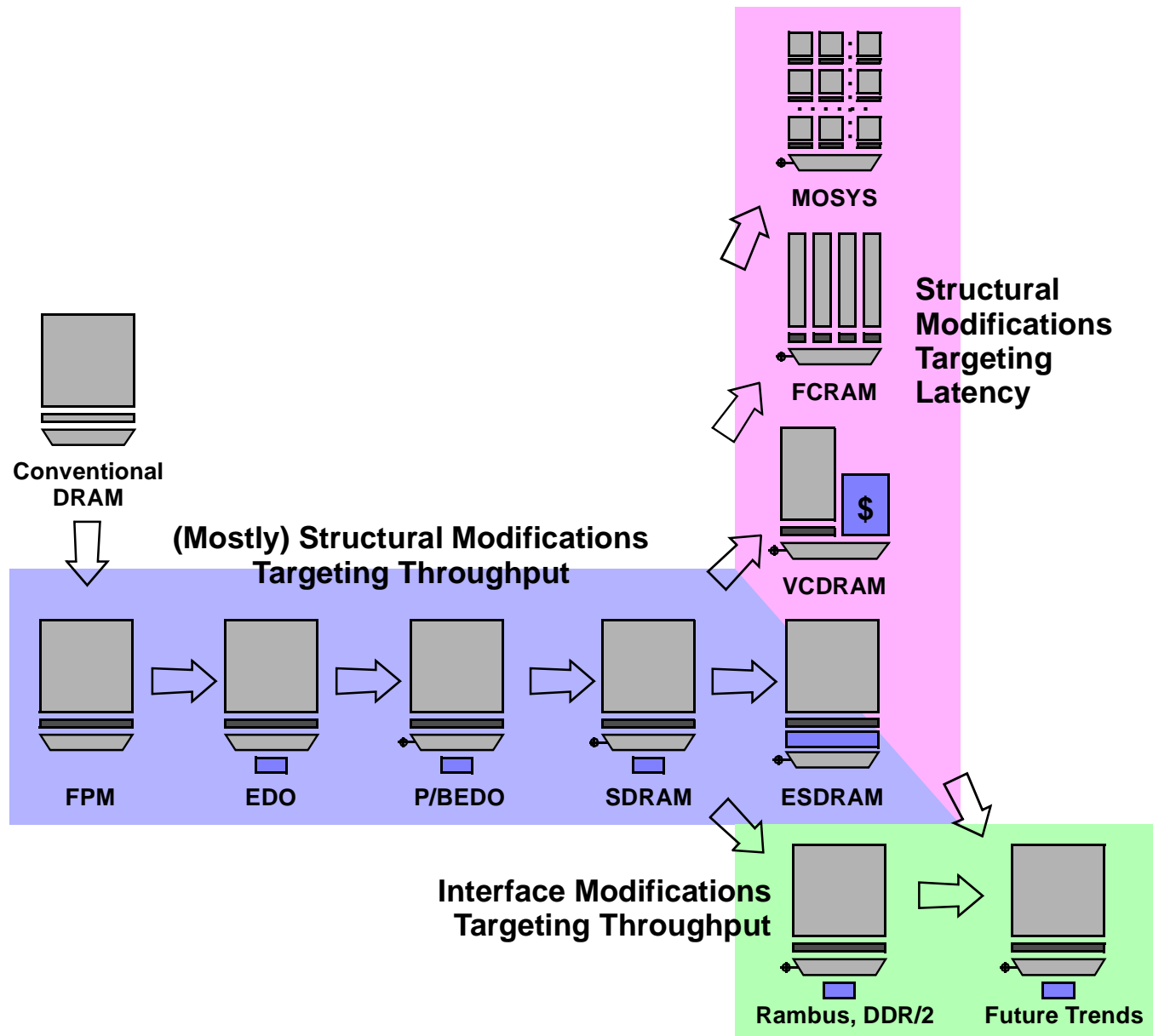
Typical DRAMs have 2+ banks

# DRAM Architecture Basics

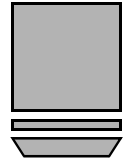
## Read Timing for Conventional DRAM



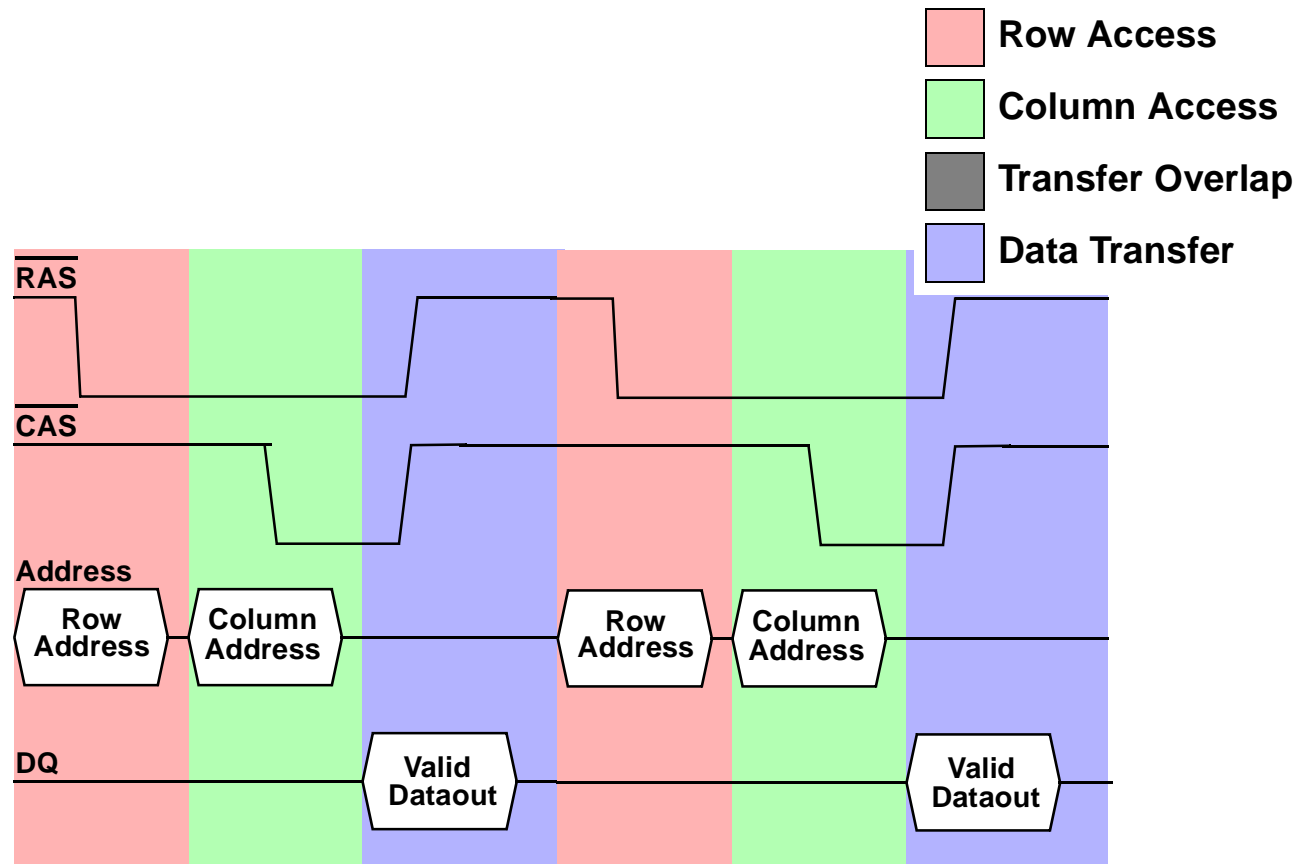
# DRAM Evolutionary Tree



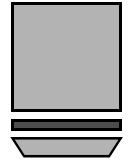
# DRAM Evolution



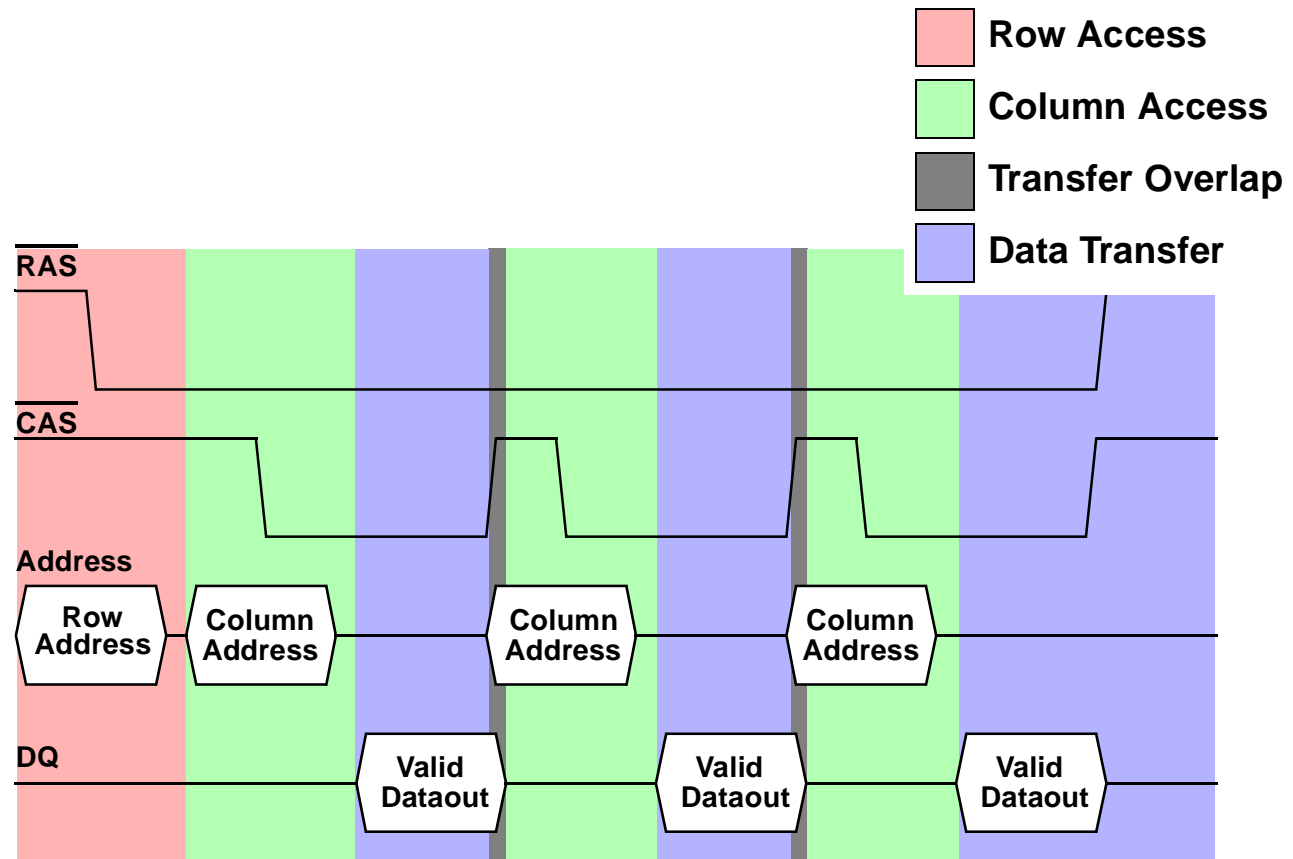
## Read Timing for Conventional DRAM



# DRAM Evolution

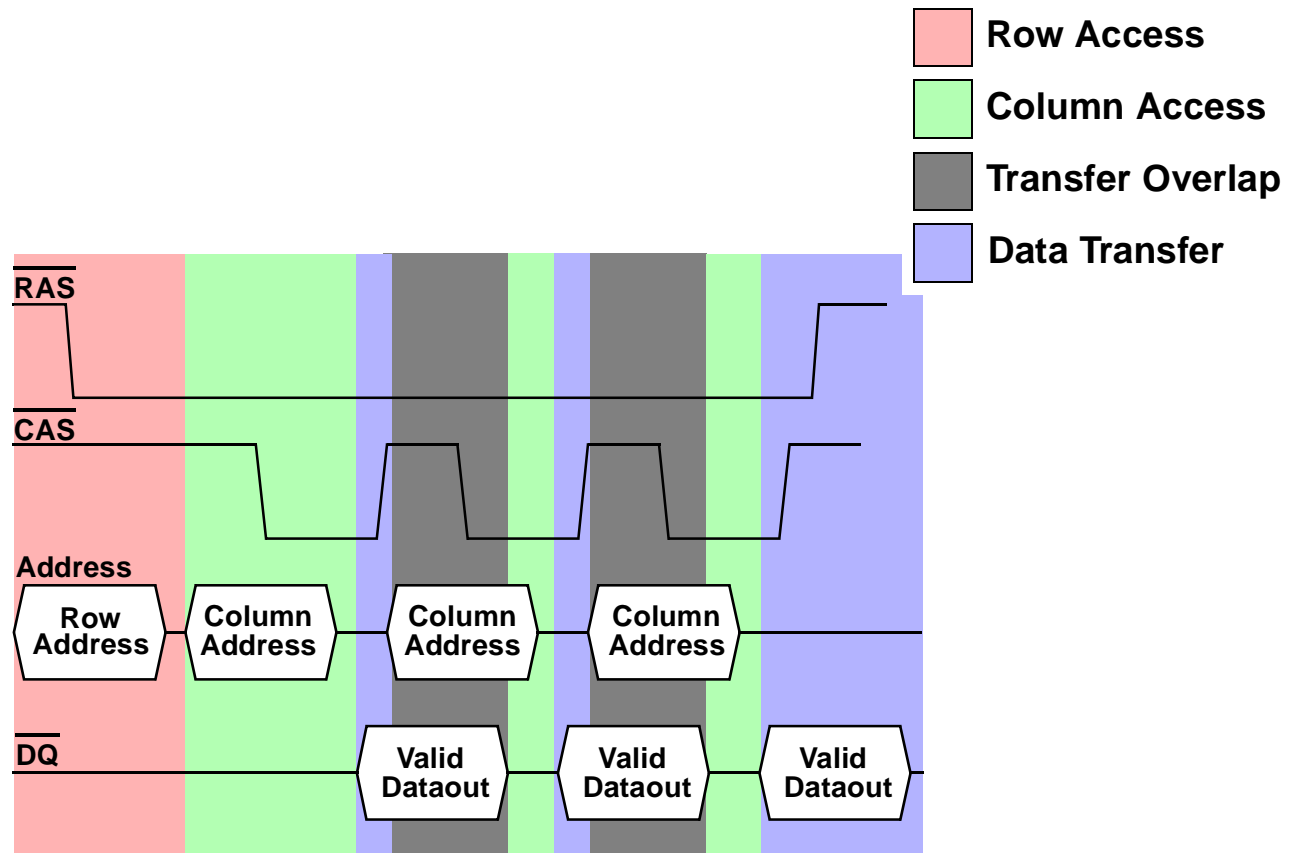
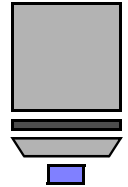


## Read Timing for Fast Page Mode



# DRAM Evolution

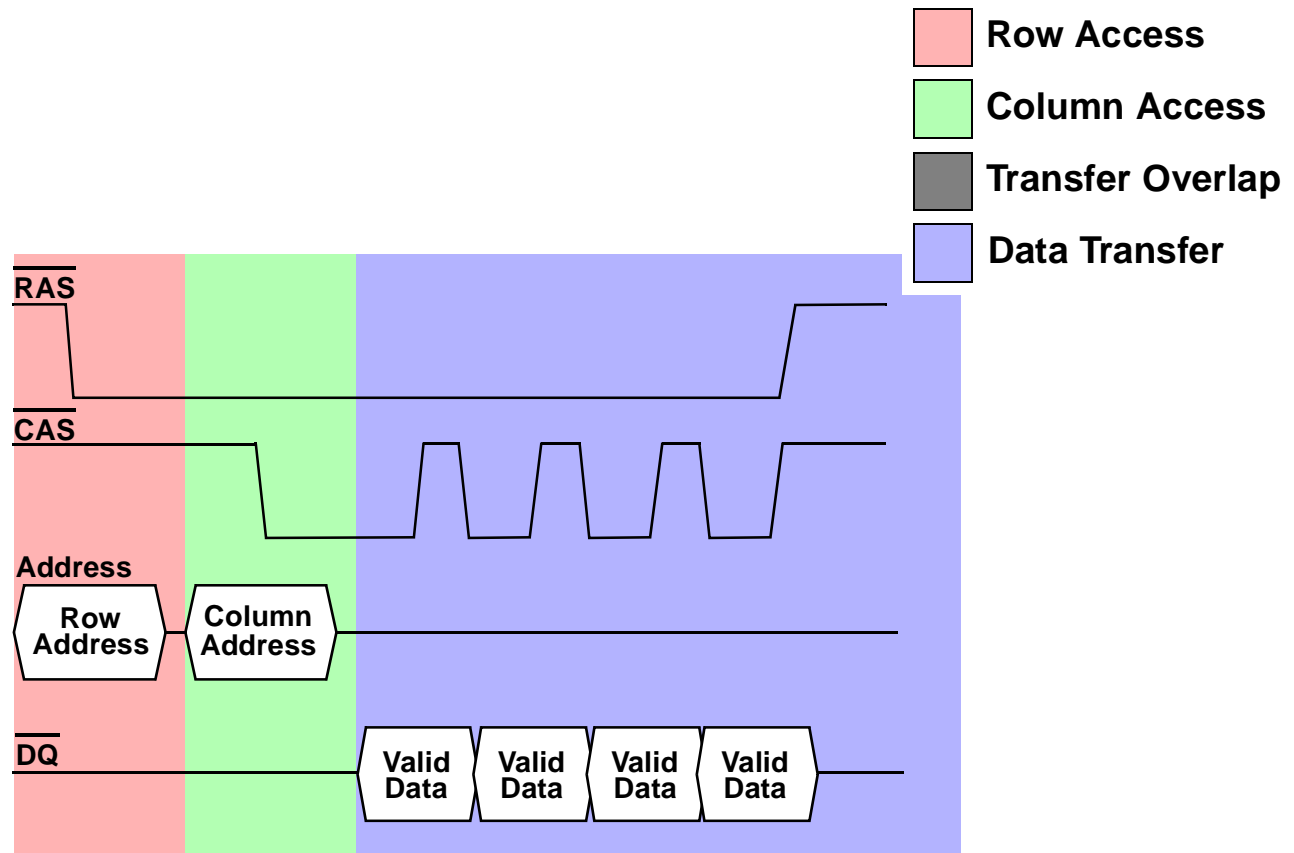
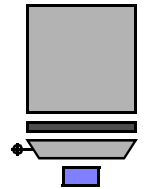
## Read Timing for Extended Data Out





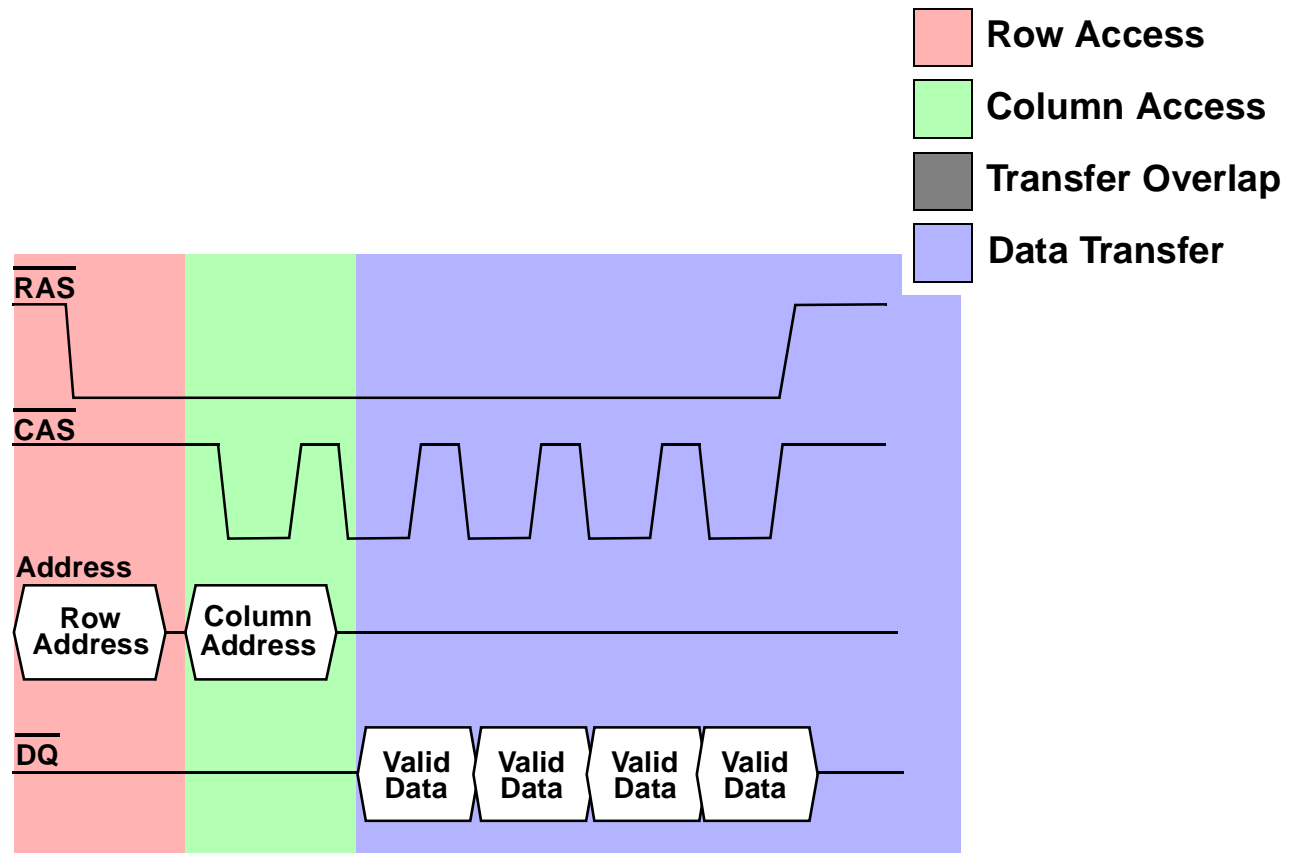
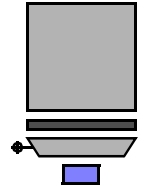
# DRAM Evolution

## Read Timing for Burst EDO

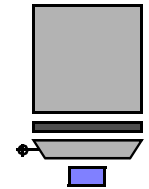


# DRAM Evolution

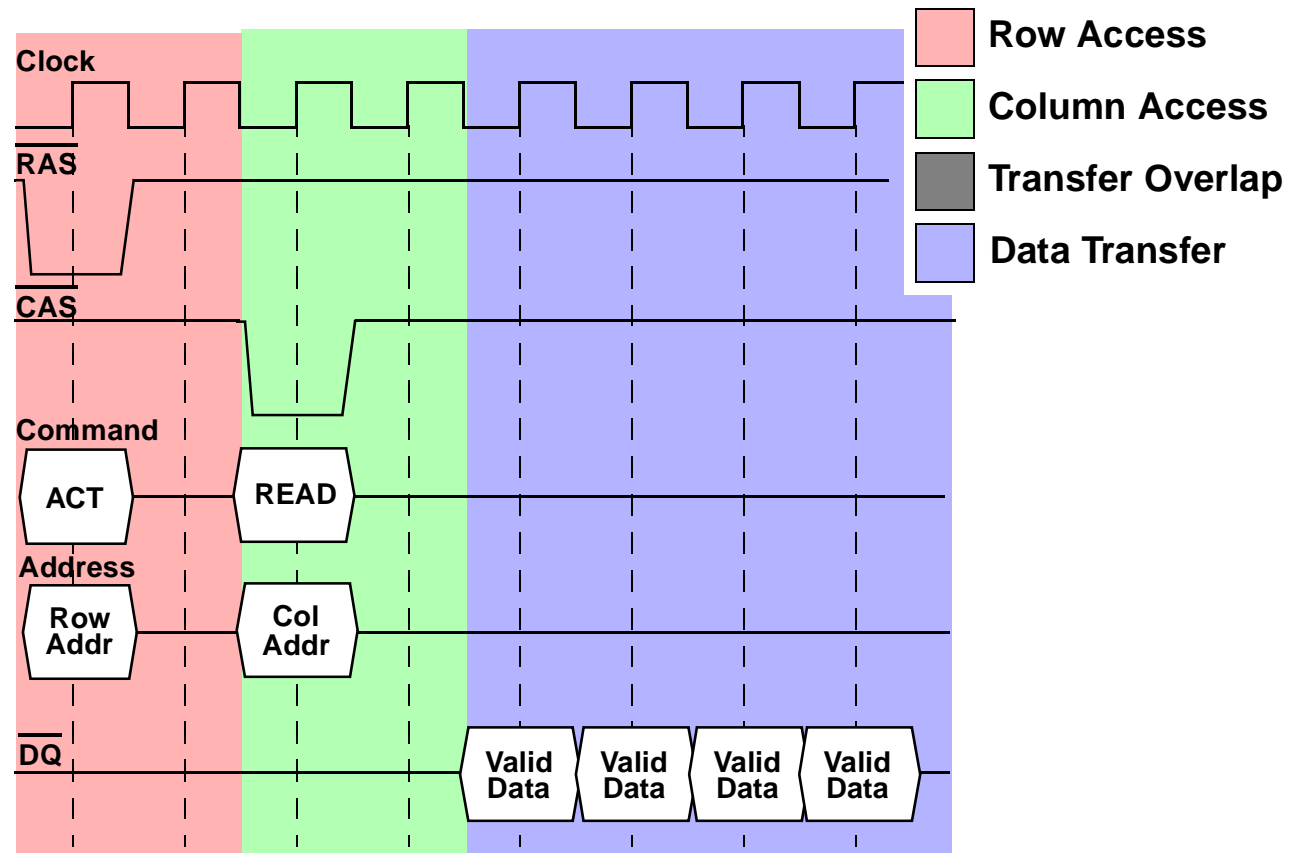
## Read Timing for Pipeline Burst EDO



# DRAM Evolution

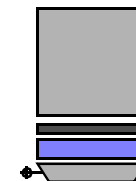


## Read Timing for Synchronous DRAM



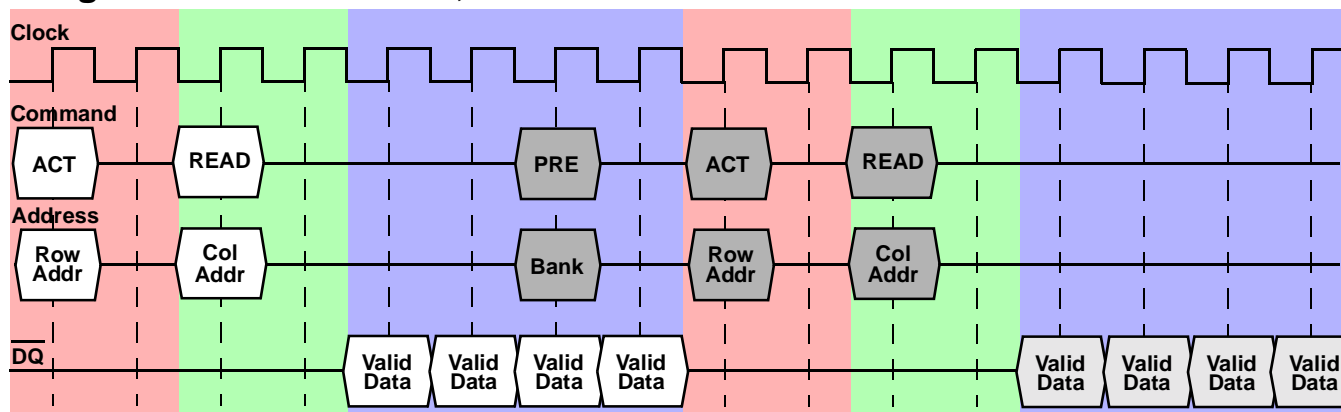
$$(\overline{\text{RAS}} + \overline{\text{CAS}} + \overline{\text{OE}} \dots == \text{Command Bus})$$

# DRAM Evolution

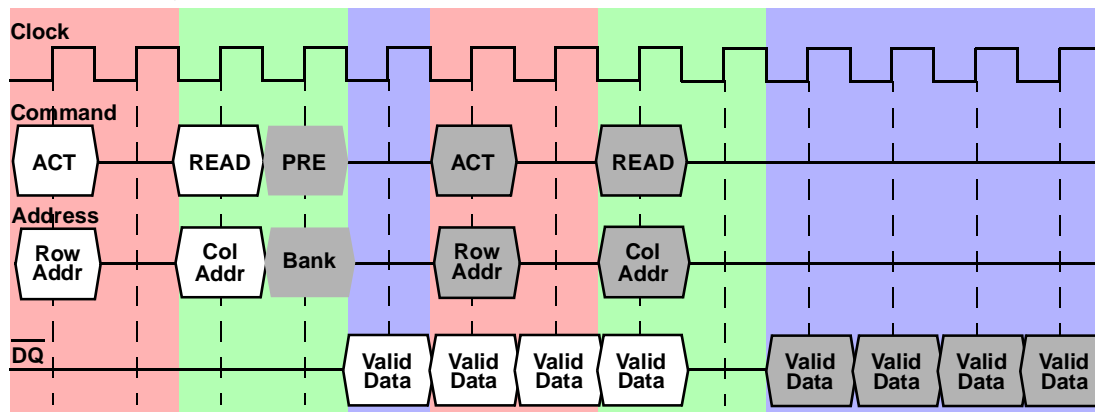


## Inter-Row Read Timing for ESDRAM

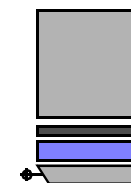
“Regular” CAS-2 SDRAM, R/R to same bank



ESDRAM, R/R to same bank

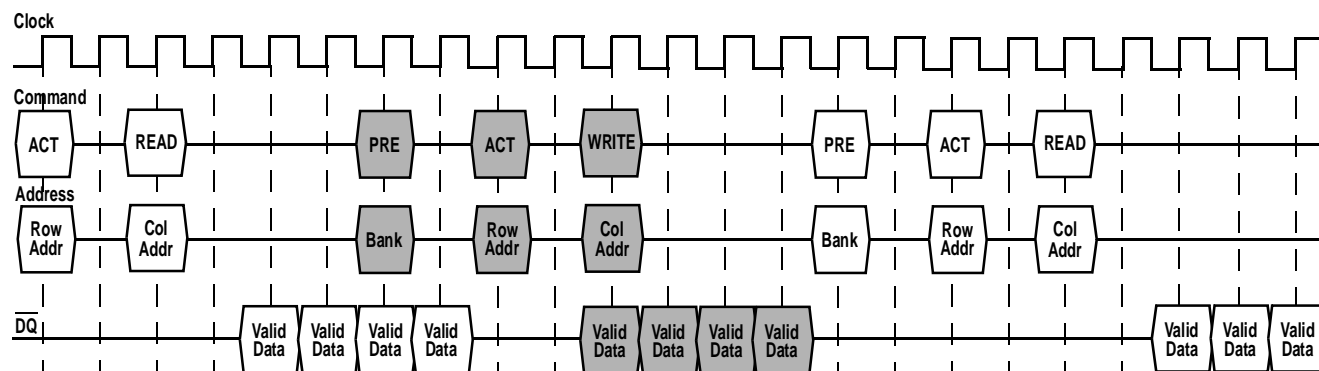


# DRAM Evolution

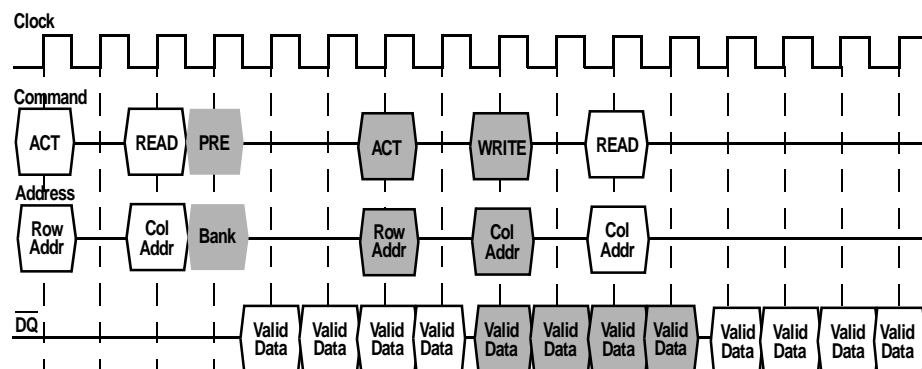


## Write-Around in ESDRAM

“Regular” CAS-2 SDRAM, R/W/R to same bank, rows 0/1/0

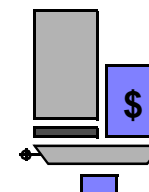


ESDRAM, R/W/R to same bank, rows 0/1/0

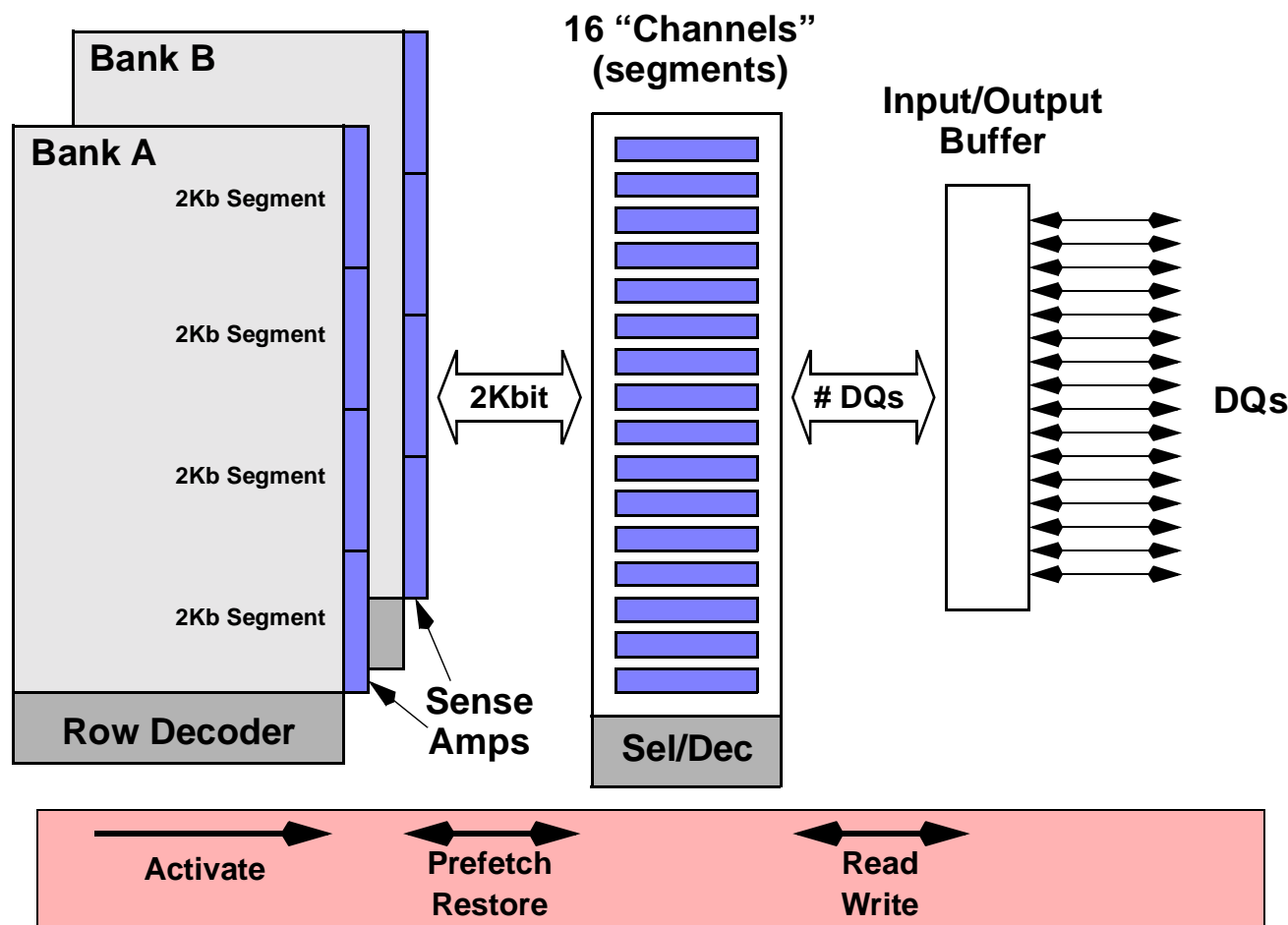


(can second READ be this aggressive?)

# DRAM Evolution

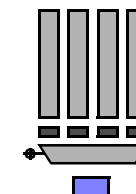


## Internal Structure of Virtual Channel

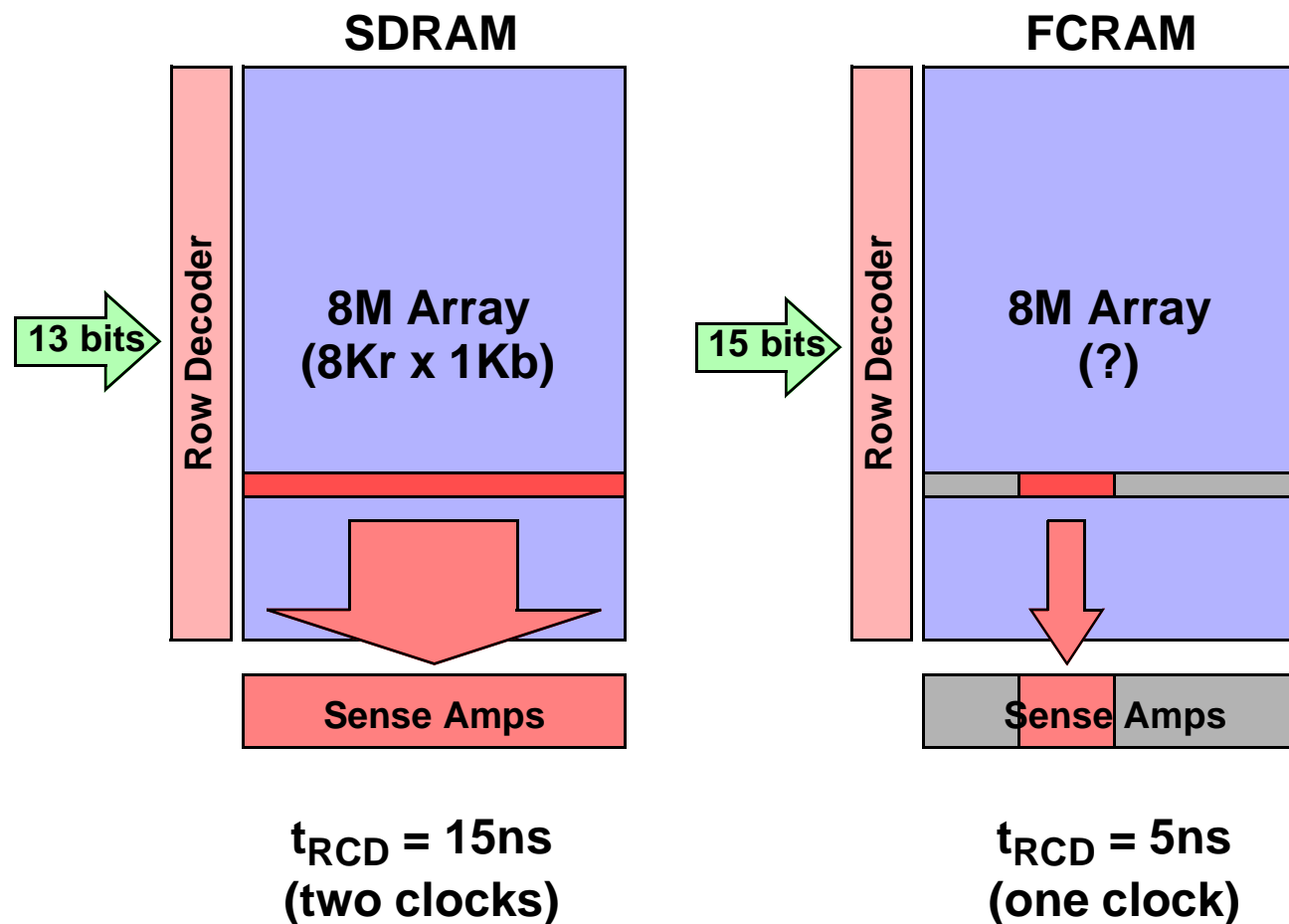


**Segment cache is software-managed, reduces energy**

# DRAM Evolution

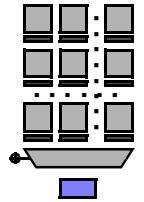


## Internal Structure of Fast Cycle RAM



Reduces access time and energy/access

# DRAM Evolution



## Internal Structure of MoSys 1T-SRAM

